

In The Title:

Please amend the title to read --METHOD FOR DISTRIBUTING CONNECTION PADS ON A SEMICONDUCTOR DIE--.

In The Specification:

On page between the title and "BACKGROUND OF THE INVENTION" insert:

CROSS-REFERENCE TO RELATED APPLICATION

This is a divisional of copending application Serial No. 08/747,325, filed November 12, 1996.

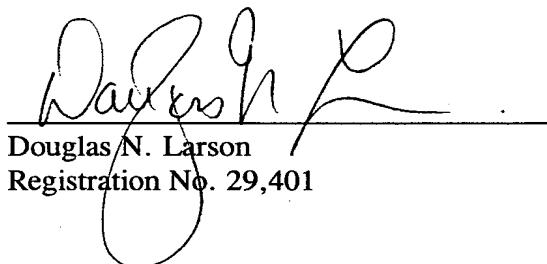
In The Claims

Please cancel without prejudice or disclaimer claims 1-21.

Remarks

It is requested that the Examiner take the foregoing into account when considering this divisional application.

Respectfully submitted,


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Dated: August 14, 1997

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